



Future Trends in Intelligent Edge Computing and Networking

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Message from the Guest Editors

Recently, mobile/multi-access edge computing (MEC) has come to play a dominant role in supporting various computational applications. To improve MEC performance in dynamical wireless environments, robust computational offloading decisions making methods and efficient wireless networking techniques are considered significant. These mostly serve as the 'brain' of MEC systems and act mostly as communication channels connecting users to the edge.

As we evolve toward the artificial intelligence of things (AIoT), our future mobile networks must support a much wider range of AI-enabled applications, such as virtual reality (VR), autonomous driving and augmented reality (AR). As a result, these and the many other new requirements call for a new computing paradigm—intelligent edge computing/edge intelligence, which has emerged as the next frontier and a cornerstone for future intelligent networks. In this context, there still exist opportunities in applying advanced machine learning technologies to facilitate the integration of computing and communications design, thereby realizing and implementing future emerging services both easily and economically.





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Message from the Editor-in-Chief

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